

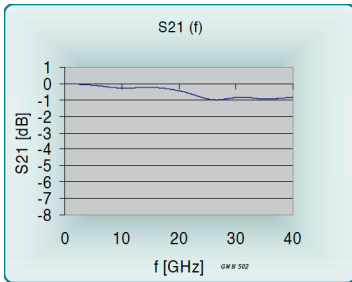


Long-Life Hi-Frequency Sockets for BGA, LGA, QFN, MLCC, μ BGA and Bumped Die Devices

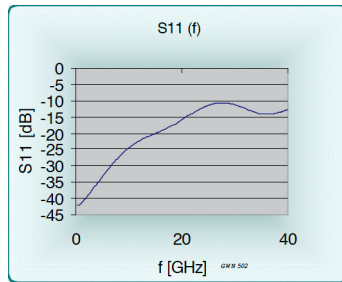
Ideally Suited for RFIC and Microwave IC Development & Test Interposer Contact System – AR200 and AR300 Series Test Sockets

Announcing significant improvements to our high-performance contact system. Using our proven Interposer Elastomer Technology, the new CORE feature internally controls compression to ensure stability with extremely low resistance values and much longer contact element life. (See Interposer Contact System Life on following page).

Low interconnect parasitics make these sockets an ideal choice for device characterization or high-volume production testing of devices, such as power amplifiers, mixers, highly integrated RF ICs, and microwave devices.



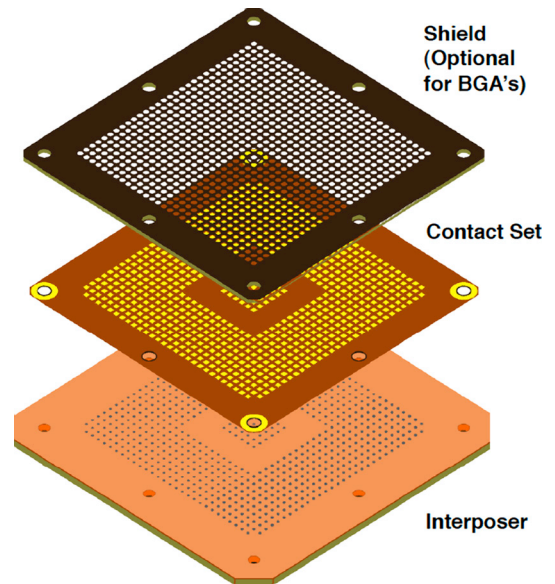
Insertion Loss of -1dB @ 40GHz



Return Loss of -15dB @ 22GHz

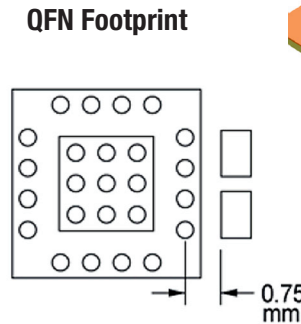
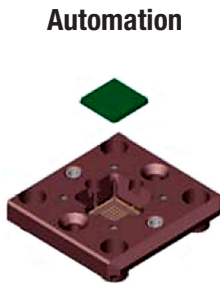
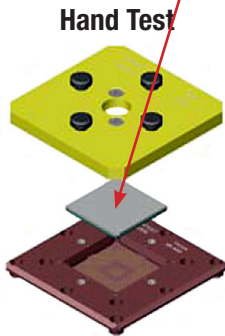
ORDERING INFORMATION

This material can be ordered with ANY [Aries RF/CSP Sockets](#)



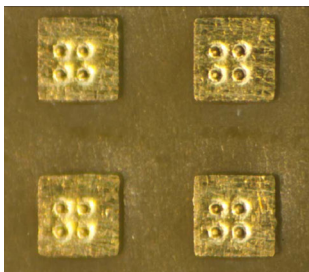
Interposer contact system with very short interconnects (available in 1.0mm or 0.6mm thickness) enhance adjacent channel power and noise sensitivity measurements.

FULL-ARRAY SHOWN AS AN EXAMPLE; YOUR SPECIFIC DEVICE PATTERN/FOOTPRINT WILL BE SUPPLIED WHEN ORDERED.

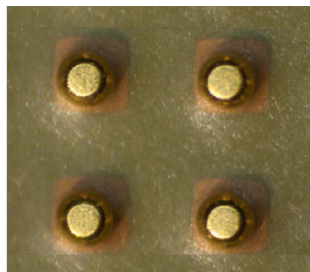


Interposer footprint lets the PCB designer locate impedance matching network components within 1mm of device pads.

CONTACT SET

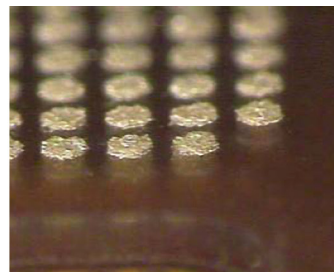


Top Side
Tips Pierce DUT

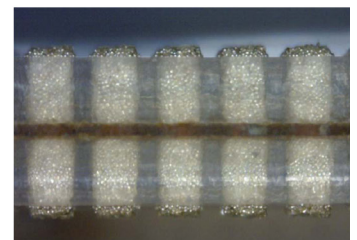


Bottom Side
Tails Compress Columns

INTERPOSER



Column Array
Elastomer Matrix Compliant Buttons



Cross Section
Ag Particles



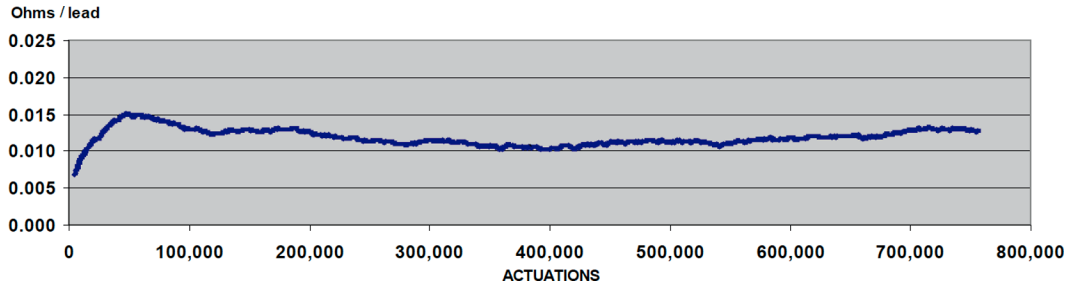
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WWW.ARIESELEC.COM • INFO@ARIESELEC.COM

24005
Rev. 1.2
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Long-Life Hi-Frequency Sockets for BGA, LGA, QFN, MLCC, μ BGA and Bumped Die Devices

High-Performance Interposer Contact Technology Suitable for Manual & Automated High-Volume Production Test



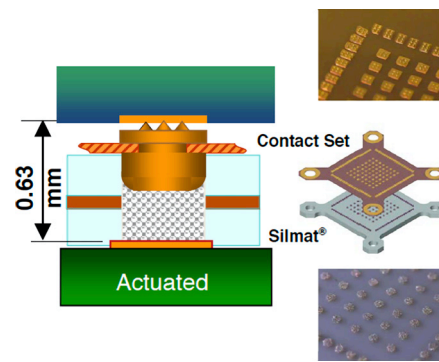
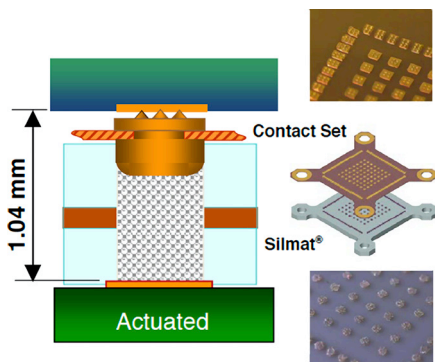
Interposer Contact System Life: QFN 0.5mm Pitch, 1.0mm Full Height

AR200 Series: 1.0mm Full Height Specifications

(measured in a 0.5mm pitch environment, GSG)
Insertion Loss S21: -1dB @ 40GHz
Return Loss S11 thru: -15dB @ 22GHz
Self Inductance: 0.33nH
Mutual Capacitance: <0.05pF
Operating Temperature: -55°C to 155°C
Contact Resistance: <25m Ω
Current Rating: 4A per lead with a 14°C rise
Contact Length (compressed): 1.04mm
Contact Force/Travel: 25-45 gf/0.4mm travel
Contact Set Life: >2,000,000 insertions
Interposer Elastomer Life: >500,000 insertions

AR300 Series: 0.6mm Half Height Specifications

(estimated 0.5mm pitch environment, GSG)
Insertion Loss S21: -1dB @ >40GHz
Return Loss S11 thru: -15dB @ >22GHz
Self Inductance: <0.15nH
Mutual Capacitance: <0.02pF
Operating Temperature: -55°C to 155°C
Contact Resistance: <25m Ω
Current Rating: 4A per lead with a 14°C rise
Contact Length (compressed): 0.63mm
Contact Force/Travel: 25-45 gf/0.28mm travel
Contact Set Life: >2,000,000 insertions
Interposer Elastomer Life: >500,000 insertions



Interposer Elastomer Conductive Columns, available in 2 Standard Heights with Standard & Custom Pitches from 1.27mm to 0.4mm



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